

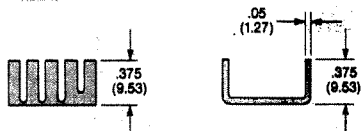
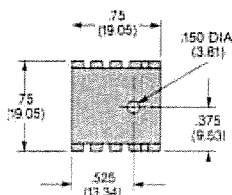
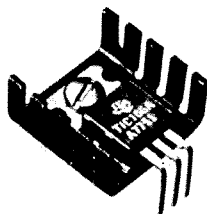
# SECTION 2

## HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

### Horizontally mounted, light-weight, low-cost heat dissipators

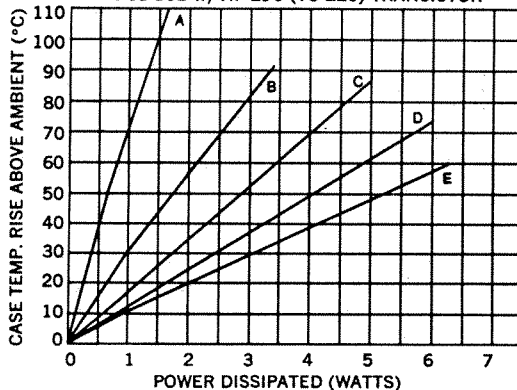
- Accommodates all flat plastic case power semiconductors.
- Efficient design requires just .71 sq. in. of board area (PA Series) and .31" to .5" height above board.
- Larger PB Series offers greater heat dissipation, additional hole patterns, and dual semiconductor mounting capability.
- Only one mounting screw required to secure dissipators to semiconductor and circuit board.
- Most effective heat dissipator in performance/unit cost.

#### PC1-1CB



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

PC1-1CB w/TIP-29C (TO-220) TRANSISTOR



#### DESCRIPTION OF CURVES

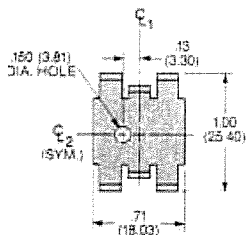
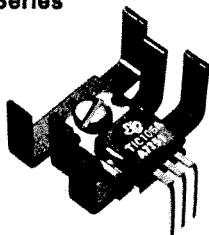
- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

#### Ordering Information

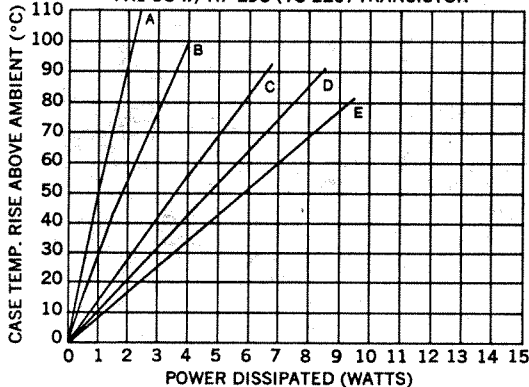
| IERC PART NO. |                       |                    | Semiconductor Accommodated | Max. Weight (Grams) |
|---------------|-----------------------|--------------------|----------------------------|---------------------|
| Unplated      | Comm'l. Black Anodize | Mil. Black Anodize |                            |                     |
| PC1-1U        | PC1-1CB               | PC1-1B             | TO-126, TO-127, TO-220     | 1.9                 |

#### PA1 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

PA1-1U w/TIP-29C (TO-220) TRANSISTOR



#### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Uprate 2.4 °C/watt for black part in natural convection only.
- Derate 0.6 °C/watt for Insulube® part in natural convection only.

#### Ordering Information

| IERC PART NO. |                      |                    |               | Semiconductor Accommodated       | Max. Weight (Grams) |
|---------------|----------------------|--------------------|---------------|----------------------------------|---------------------|
| Unplated      | Com'l. Black Anodize | Mil. Black Anodize | Insulube® 448 |                                  |                     |
| PA1U          | PA1CB                | PA1B               | PA1           | Undrilled TO-126, TO-127, TO-220 | 2.0                 |
| PA1-1U        | PA1-1CB              | PA1-1B             | PA1-1         |                                  | 2.0                 |

Note: See page Iv for other finishes.

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

CTS:

PA1-1CB